

Call for Papers

Austrochip is the traditional annual workshop on microelectronics and integrated circuits in Austria and neighboring countries. The 27th edition will be organized by the Department of Electronics Engineering, Research Group Embedded Systems, FH Technikum Wien.

Topics of the workshop include but are not limited to:

- Analog, mixed-signal, and RF integrated circuits
- Digital circuits, filters, DSPs, asynchronous designs
- FPGA design and reconfigurable hardware
- Design methodology, system-level design, high-level synthesis, gigascale circuits, networks-on-chip
- Embedded systems, low-power design, fault-tolerant design, RF systems, security and safety aspects
- Verification and testing, signal integrity, device modelling, timing analysis, reliability simulation, EMC, ESD
- Emerging technologies, nanoCMOS process technologies, sub-threshold circuits, sensors, organic and biomedical electronics
- Case studies and prototyping

Submissions from both academia as well as from the industry are welcome. We especially invite PhD students to present their ongoing work but also content from excellent MSc theses in the field of the previously mentioned conference topics will be considered. Submissions will be double-blind-reviewed. Papers accepted by the program committee will be made available electronically at the conference and we plan to publish all papers written in English through IEEE Xplore (with indexing by well-known major indexing services).

Instructions for Authors

Papers should have a length from 4-8 pages and must meet the IEEE format. Instructions and additional details can be found at <https://embsys.technikum-wien.at/austrochip2019/submission/>

Conference Venue

Austrochip 2019 is held in Vienna on Oct. 24, 2019, at FH Technikum Wien, Höchstädtplatz 6, 1200 Vienna. Conference registration includes access to all sessions, proceedings, lunch and coffee breaks.

Contact/Organization

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Conference Venue



[FH Technikum Wien](#)

Important Dates

Submission Deadline

Sept. 9, 2019 (**Extended!**)

Acceptance Notification

September 23, 2019

Conference Date

October 24, 2019

Organizer



[Research Group
Embedded Systems](#)

Technical Co-sponsors



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